



Customer Information Notification

201612014I

Issue Date: 27-Jan-2017
Effective Date: 28-Jan-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | | |
|--|---|--|---|--|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input checked="" type="checkbox"/> Electrical spec./Test coverage |

SAC57D54H General Market Datasheet Update to rev6

Information Notification

The Datasheet for SAC57D54H has been updated to revision 6 from revision 5. The following are the pages that were updated:

1. Removed a paragraph in page 10 of the datasheet under 'Recommended operating conditions'.
2. Page 13 of the datasheet includes Table 5 Voltage monitor electrical specifications.
- Updated VLVD_IO_A_LO fall trimmed values 'Typ' and 'Max' from 3.0390V and 3.1000V to 3.0260 V and 3.0750 V respectively.
3. Page 36 of the datasheet includes Table 32 Flash memory program and erase specifications.
4. Page 38 of the datasheet includes Table 35 Flash memory AC timing specifications
5. The revision history included in the updated document provides a detailed description of the changes.

The Datasheet for SAC57D54H can be found at http://www.nxp.com/products/microcontrollers-and-processors/arm-processors/mac57dxxx/ultra-reliable-multi-core-arm-based-mcu-for-clusters-and-display-management:MAC57D5xx?tab=Documentation_Tab

Why do we issue this Information Notification

The Datasheet for SAC57D54H has been updated to correct errors and provide additional technical clarification on some device features.

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Keng How Quek
Position Product Engineer
e-mail address keng.quek@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP | Privacy Policy | Terms of Use](#)

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Affected Part Numbers

SAC57D54HCVLT

SAC57D54HCVMO

SAC57D54HCVMO